COMPLIANT

HALOGEN

FREE



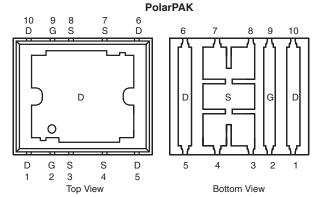


N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY									
		I _D (A) ^a						
V _{DS} (V)	R _{DS(on)} (Ω) ^e	Silicon Limit	Package Limit	Q _g (Typ.)					
30	$0.0019 \text{ at V}_{GS} = 10 \text{ V}$	202	60	50 nC					
30	0.0026 at $V_{GS} = 4.5 \text{ V}$	173	60	30110					

Package Drawing

www.vishay.com/doc?72945



Top surface is connected to pins 1, 5, 6, and 10

Ordering Information: SiE802DF-T1-E3 (Lead (Pb)-free)

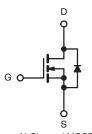
SiE802DF-T1-GE3 (Lead (Pb)-free and Halogen-free)

FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Gen II Power MOSFET
- Ultra Low Thermal Resistance Using Top-Exposed PolarPAK® Package for Double-Sided Cooling
- Leadframe-Based New Encapsulated Package
 - Die Not Exposed
 - Same Layout Regardless of Die Size
- Low Q_{gd}/Q_{gs} Ratio Helps Prevent Shoot-Through 100 % R_g and UIS Tested
- Compliant to RoHS directive 2002/95/EC

APPLICATIONS

- **VRM**
- DC/DC Conversion: Low-Side
- Synchronous Rectification



N-Channel MOSFET For Related Documents www.vishay.com/ppg?72985

ABSOLUTE MAXIMUM RATIN	IGS T _A = 25 °C,	unless otherwis	se noted	
Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	± 20	v
	T _C = 25 °C		202 (Silicon Limit)	
	10 = 25 C		60 ^a (Package Limit)	
Continuous Drain Current (T _J = 150 °C)	T _C = 70 °C	I _D	60 ^a	
	T _A = 25 °C		42.7 ^{b, c}	
	T _A = 70 °C		34.2 ^{b, c}	Α
Pulsed Drain Current		I _{DM}	100	
Continuous Course Drain Diade Current	T _C = 25 °C		60 ^a	
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	4.3 ^{b, c}	
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	50	
Avalanche Energy	L = U.1 IIII	E _{AS}	125	mJ
	T _C = 25 °C		125	
Maximum Power Dissipation	T _C = 70 °C	P _D	80	W
	T _A = 25 °C	' D	5.2 ^{b, c}	VV
	T _A = 70 °C		3.3 ^{b, c}	
Operating Junction and Storage Temperatur	e Range	T _J , T _{stq}	- 55 to 150	°C
Soldering Recommendations (Peak Tempera	ature) ^{d, e}	1 13	260	

- a. Package limited is 60 A.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 10 s.
- d. See Solder Profile (www.vishay.com/doc?73257). The PolarPAK is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- e. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.

SiE802DF

Vishay Siliconix



THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^{a, b}	t ≤ 10 s	R _{thJA}	20	24			
Maximum Junction-to-Case (Drain Top)	Steady State	R _{thJC} (Drain)	0.8	1	°C/W		
Maximum Junction-to-Case (Source)a, c	Steady State	R _{thJC} (Source)	2.2	2.7			

Notes:

- a. Surface Mounted on 1" x 1" FR4 board.
- b. Maximum under Steady State conditions is 68 $^{\circ}\text{C/W}.$
- c. Measured at source pin (on the side of the package).

Parameter	Symbol Test Conditions		Min.	Тур.	Max.	Unit
Static				•		
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	30			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 050 ·· A		32.2		
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 6.4		mV/°C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_{D} = 250 \mu A$	1.5	2.2	2.7	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zana Cata Valtana Duain Comunant	_	V _{DS} = 30 V, V _{GS} = 0 V			1	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			10	μΑ
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	25			Α
D : 0	В	$V_{GS} = 10 \text{ V}, I_D = 23.6 \text{ A}$		0.0016	0.0019	0
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 21.3 \text{ A}$		0.0021	0.0026	Ω
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 15 \text{ V}, I_D = 23.6 \text{ A}$	(, I _D = 23.6 A 156			S
Dynamic ^b				•		
Input Capacitance	C _{iss}			7000		
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		1200		рF
Reverse Transfer Capacitance	C _{rss}	50		500		1
Tatal Cata Chausa	Qg	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 23.6 \text{ A}$		105	160	
Total Gate Charge				50	75	
Gate-Source Charge	Q_{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 23.6 \text{ A}$		21		nC
Gate-Drain Charge	Q_{gd}			14		
Gate Resistance	R _q	f = 1 MHz		1.1	1.65	Ω
Turn-On Delay Time	t _{d(on)}			45	70	
Rise Time	ì,	$V_{DD} = 15 \text{ V}, R_L = 1.5 \Omega$		195	300	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		45	70	
Fall Time	Ì _f	· ·		20	30	
Turn-On Delay Time	t _{d(on)}			25	40	ns
Rise Time	ì,	$V_{DD} = 15 \text{ V}, R_L = 1.5 \Omega$		20	30	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_q = 1 \Omega$		65	100	
Fall Time	ì _f	Ç		10	15	1
Drain-Source Body Diode Characteristic	s					
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			60	^
Pulse Diode Forward Current ^a	I _{SM}				100	Α
Body Diode Voltage	V _{SD}	I _S = 10 A		0.8	1.2	V
Body Diode Reverse Recovery Time	t _{rr}	-		55	85	ns
Body Diode Reverse Recovery Charge	Q _{rr}	1 10 A dl/dt 100 A/ T 05 00		66	105	nC
Reverse Recovery Fall Time	t _a	$I_F = 10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		25		
Reverse Recovery Rise Time	t _b			30		ns

Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





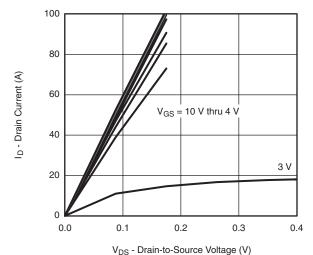


0.0019

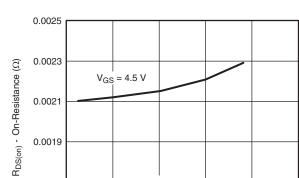
0.0017

0.0015

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



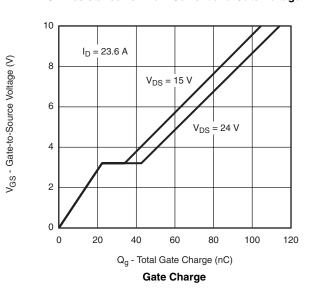
Output Characteristics



 $V_{GS} = 10 \text{ V}$ 20

100

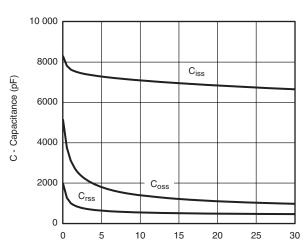
I_D - Drain Current (A) On-Resistance vs. Drain Current and Gate Voltage



20 16 I_D - Drain Current (A) 12 8 T_C = 125 °C 4 55 °C 0.0 0.5 1.0 1.5 2.0 2.5 3.0 3.5

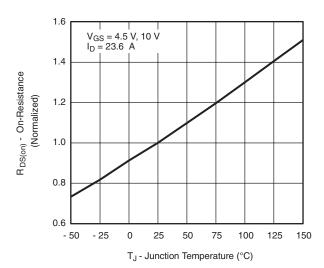
V_{GS} - Gate-to-Source Voltage (V)





V_{DS} - Drain-to-Source Voltage (V)

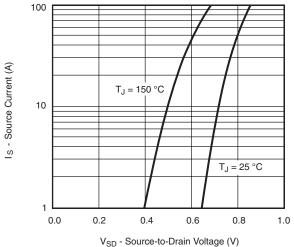
Capacitance



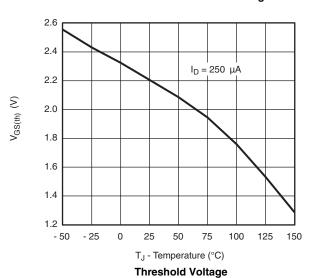
On-Resistance vs. Junction Temperature

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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

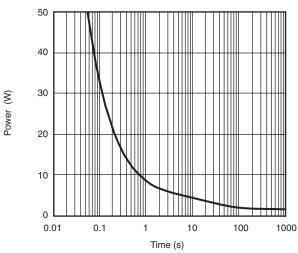


Source-Drain Diode Forward Voltage

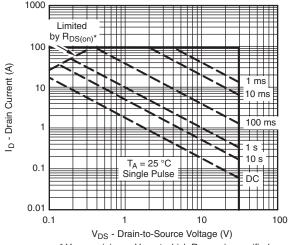


0.0040 0.0035 0.0030 0.0025 0.0020 0.0020 0.0010 0 2 4 6 8 10 V_{GS} - Gate-to-Source Voltage (V)

On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient



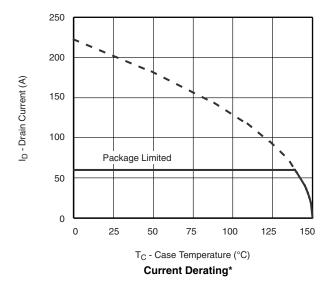
* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

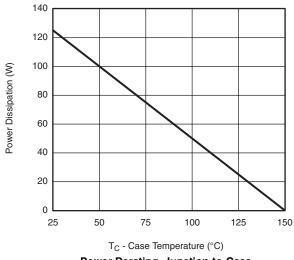
Safe Operating Area, Junction-to-Ambient





TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



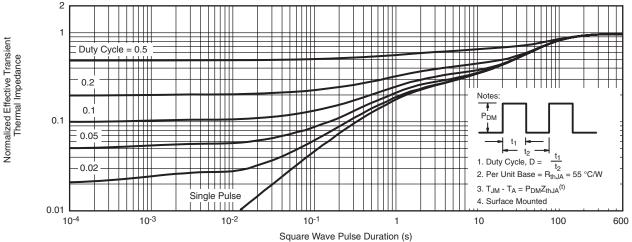


Power Derating, Junction-to-Case

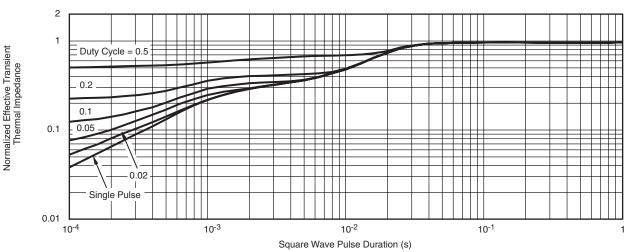
^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

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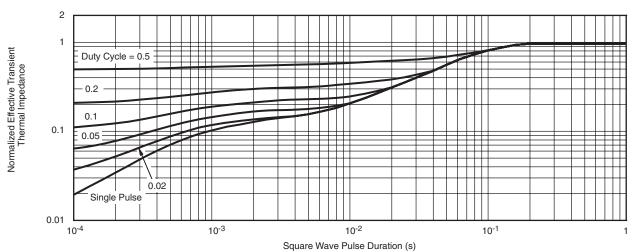
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case (Drain Top)

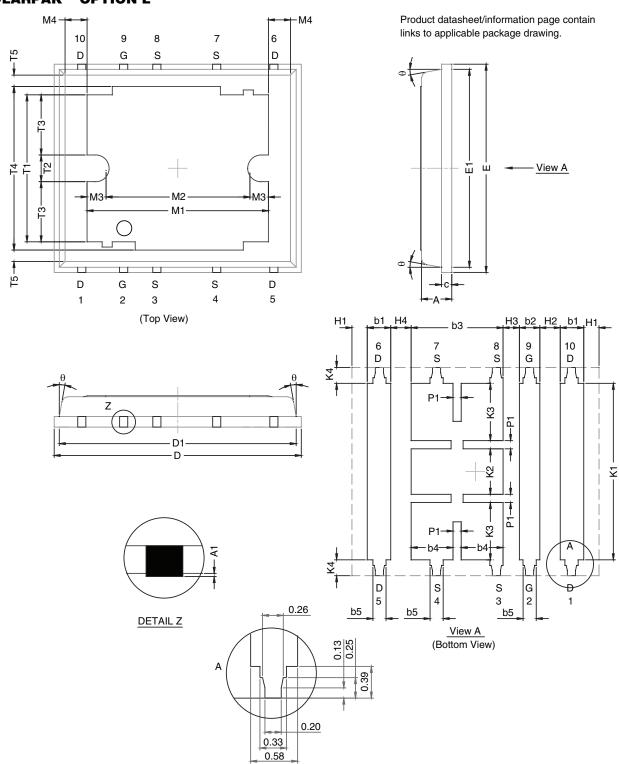


Normalized Thermal Transient Impedance, Junction-to-Source

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?72985.



POLARPAK™ OPTION L



Package Information

Vishay Siliconix



	MILLIMETERS				INCHES		
DIM	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
Α	0.75	0.80	0.85	0.030	0.031	0.033	
A1	0.00	-	0.05	0.000	-	0.002	
b1	0.48	0.58	0.68	0.019	0.023	0.027	
b2	0.41	0.51	0.61	0.016	0.020	0.024	
b3	2.19	2.29	2.39	0.086	0.090	0.094	
b4	0.89	1.04	1.19	0.035	0.041	0.047	
b5	0.23	0.33	0.43	0.009	0.013	0.017	
С	0.20	0.25	0.30	0.008	0.010	0.012	
D	6.00	6.15	6.30	0.236	0.242	0.248	
D1	5.74	5.89	6.04	0.226	0.232	0.238	
E	5.01	5.16	5.31	0.197	0.203	0.209	
E1	4.75	4.90	5.05	0.187	0.193	0.199	
H1	0.23	-	-	0.009	-	-	
H2	0.45	-	0.56	0.018	-	0.022	
H3	0.31	0.41	0.51	0.012	0.016	0.020	
H4	0.45	-	0.56	0.018	-	0.022	
K1	4.22	4.37	4.52	0.166	0.172	0.178	
K2	1.08	1.13	1.18	0.043	0.044	0.046	
K3	1.37	-	-	0.054	-	-	
K4	0.24	-	-	0.009	-	-	
M1	4.30	4.50	4.70	0.169	0.177	0.185	
M2	3.43	3.58	3.73	0.135	0.141	0.147	
МЗ	0.22	-	-	0.009	-	-	
M4	0.05	-	-	0.002	-	-	
P1	0.15	0.20	0.25	0.006	0.008	0.010	
T1	3.48	3.64	4.10	0.137	0.143	0.161	
T2	0.56	0.76	0.95	0.022	0.030	0.037	
T3	1.20	-	-	0.047	-	=	
T4	3.90	-	-	0.153	-	-	
T5	0	0.18	0.36	0.000	0.007	0.014	
θ	0°	10°	12°	0°	10°	12°	

DWG: 5946

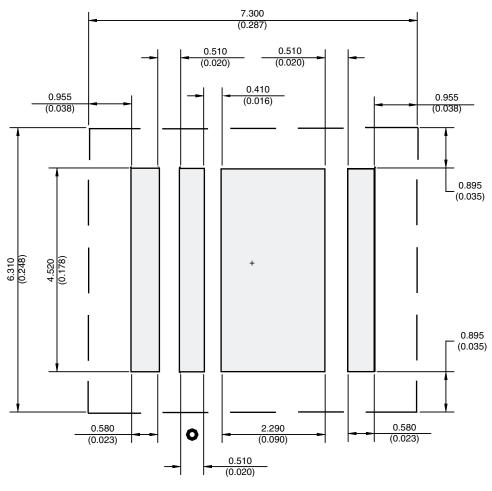
Notes

Millimeters govern over inches.

APPLICATION NOTE



RECOMMENDED MINIMUM PADS FOR PolarPAK® Option L and S



Recommended Minimum for PolarPAK Option L and S Dimensions in mm/(Inches) No External Traces within Broken Lines Dot indicates Gate Pin (Part Marking)

Return to Index





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Document Number: 91000 www.vishay.com Revision: 11-Mar-11